



Connectors > Card & Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: Double Data Rate (DDR)

Stack Height: 5.2 mm [.205 in]

Module Orientation: Right Angle

PCB Mounting Style: Surface Mount

Connector System: Cable-to-Board

Features

Product Type Features

DRAM Type	Double Data Rate (DDR)
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Bays	2
Center Key	None
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	200
Number of Rows	2
Keying	Standard

Electrical Characteristics

DRAM Voltage	2.5 V
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Signal Characteristics

SGRAM Voltage	2.5 V
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Body Features

Ejector Location	Both Ends
Latch Material	Stainless Steel
Latch Plating Material	Tin
Module Key Type	SGRAM
Ejector Type	Locking
Connector Profile	Standard

Contact Features

Socket Style	SO DIMM
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A
Socket Type	Memory Card

Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
PCB Mounting Style	Surface Mount
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	.6 mm[.024 in]
Housing Color	Black
Housing Material	High Temperature Thermoplastic

Dimensions

Stack Height	5.2 mm[.205 in]
Row-to-Row Spacing	6.2 mm[.244 in]

Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Tape & Reel
Packaging Quantity	150

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2020 (205) Candidate List Declared Against: JAN 2020 (205) Does not contain REACH SVHC
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2020 (205) Candidate List Declared Against: JAN 2020 (205)
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles'(Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.




Compatible Parts



TE Model / Part # 2309407-1
DDR4 SODIMM 260P 4.0H STD

Also in the Series


DDR SODIMM




SO DIMM Sockets(7)

Also in the Series

DDR3 SO DIMM



DIMM Sockets(9)



SO DIMM Sockets(3)

Customers Also Bought



TE Model / Part #2199230-3
M.2 0.5PITCH 4.2H KEY B 15U" AU



TE Model / Part #2199119-4
M.2 0.5PITCH 3.2H KEY E 15U" AU



TE Model / Part #2199119-3
M.2 0.5PITCH 3.2H KEY B 15U" AU



TE Model / Part #1717254-4
EMBOSS ASSY DDR2 SODIMM
SOCKET 200P 5.2H



TE Model / Part #1-1734248-5
1.0 FPC, ZIF V/T, SMT, 15P



TE Model / Part #1-2176230-4
3522 10R 5% 3W



TE Model / Part #1-1614959-1
CPF0805 1M5 0.1% 25PPM 1K RL



TE Model / Part #1473149-4
SEMI-HARD TRAY ASSY DDR2
SODIMM 5.2H ST



TE Model / Part #1612618-1
DDR SODIMM SOCKET 200POS SEMI-

Documents

Product Drawings

EMBOSS ASS'Y DDR SODIMM SOCKET

English

CAD Files

Customer View Model

ENG_CVM_CVM_1717254-1_D1.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1717254-1_D1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1717254-1_D1.3d_stp.zip

English

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Product Specifications

Product Specification

English

Product Environmental Compliance

TE Material Declaration

English